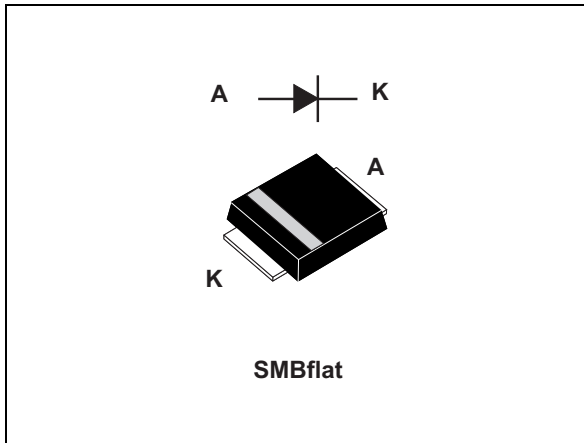


Automotive Turbo 2 ultrafast high voltage rectifier

Datasheet - production data



Features

- Ultrafast recovery
- Low conduction losses
- High surge capability
- Low leakage current
- High junction temperature
- AEC-Q101 qualified
- ECOPACK[®]2 compliant component
- V_{RRM} guaranteed from -40 to +175 °C

Description

The STTH3L06-Y is an ultrafast recovery power rectifier dedicated to energy recovery in automotive application housed in SMBflat to improve space saving.

It is especially designed for clamping function in energy recovery block.

The compromise between forward voltage drop and recovery time offers optimized performances.

Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	3 A
V_{RRM}	600 V
$T_{j(max)}$	175 °C
V_F (typ)	0.9 V
T_{rr} (typ)	50 ns

1 Characteristics

Table 2. Absolute ratings (limiting values at $T_j = 25\text{ °C}$, unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage	$T_j = -40\text{ to }+175\text{ °C}$	600	V
$I_{F(AV)}$	Average forward current, square waveform	$T_L = 110\text{ °C } \delta = 0.5$	3	A
I_{FSM}	Forward Surge current	$t_p = 10\text{ ms}$	30	A
T_{stg}	Storage temperature range		-65 to + 175	°C
$T_j^{(1)}$	Operating temperature range		-40 to + 175	°C

1. $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
$R_{th(j-l)}$	Junction to lead	16	°C/W

Table 4. Static electrical characteristics

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = 600\text{ V}$	-		3	μA
		$T_j = 150\text{ °C}$		-	15	100	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 3\text{ A}$	-		1.4	V
		$T_j = 150\text{ °C}$		-	0.9	1.15	

1. Pulse test: $t_p = 5\text{ ms}$, $\delta < 2\%$

2. Pulse test: $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.95 \times I_{F(AV)} + 0.067 \times I_F^2_{(RMS)}$$

Table 5. Dynamic electrical characteristics

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	$T_j = 25\text{ °C}$	$I_F = 1\text{ A}$, $dI_F/dt = -50\text{ A}/\mu\text{s}$ $V_R = 30\text{ V}$	-	50	70	ns
t_{fr}	Forward recovery time	$T_j = 25\text{ °C}$	$I_F = 3\text{ A}$, $dI_F/dt = 100\text{ A}/\mu\text{s}$, $V_{FR} = 1.6\text{ V}$	-		130	
V_{FP}	Forward recovery voltage			-			5

Figure 1. Average forward power dissipation versus average forward current

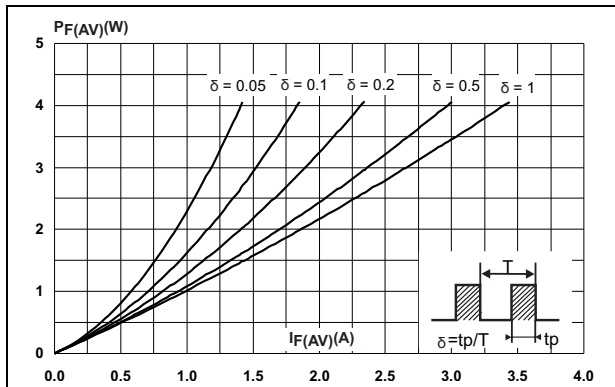


Figure 2. Forward voltage drop versus forward current (typical values)

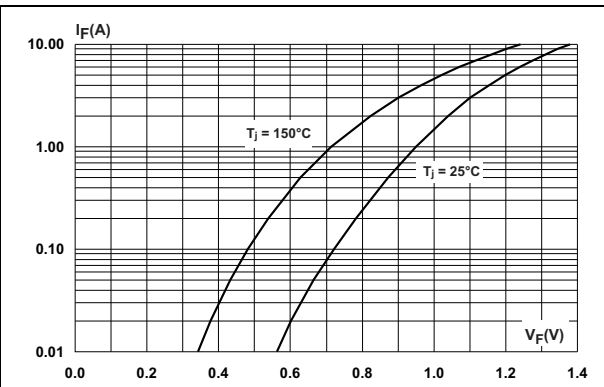


Figure 3. Forward voltage drop versus forward current (maximum values)

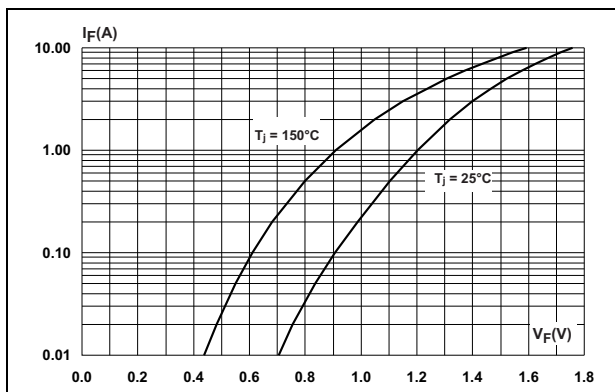


Figure 4. Relative variation of thermal impedance junction to lead versus pulse duration

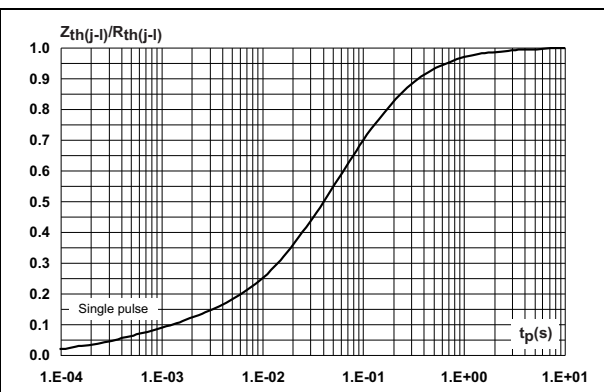


Figure 5. Peak reverse recovery current versus dIF/dt (typical values)

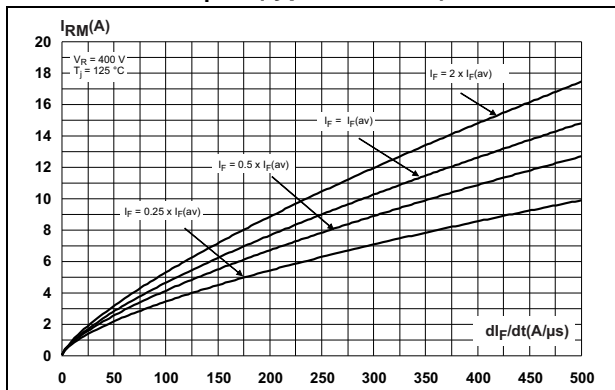


Figure 6. Reverse recovery time versus dIF/dt (typical values)

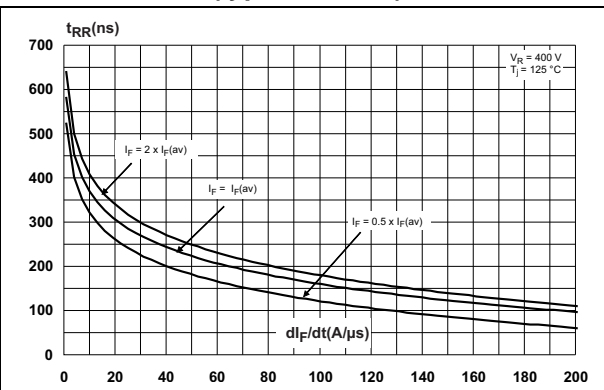


Figure 7. Reverse recovery charges versus di_F/dt (typical values)

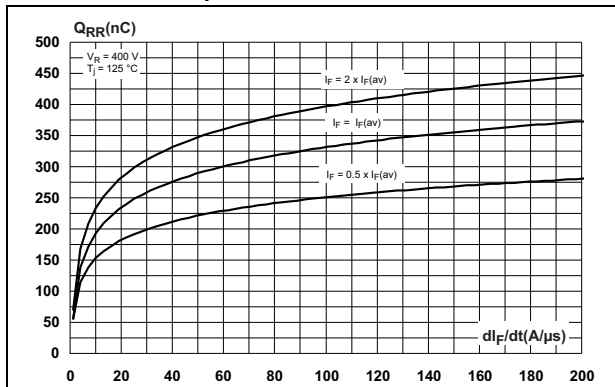


Figure 8. Reverse recovery softness factor versus di_F/dt (typical values)

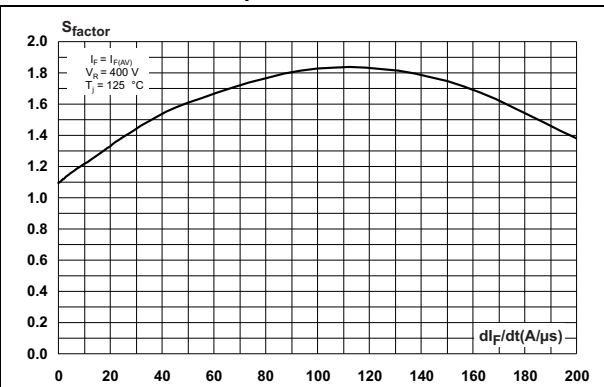


Figure 9. Relative variation of dynamic parameters versus junction temperature

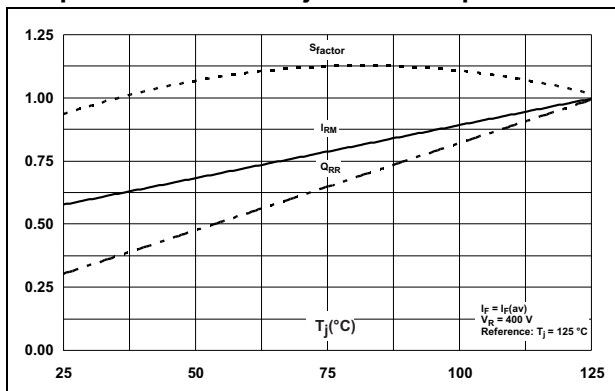


Figure 10. Transient peak forward voltage versus di_F/dt (typical values)

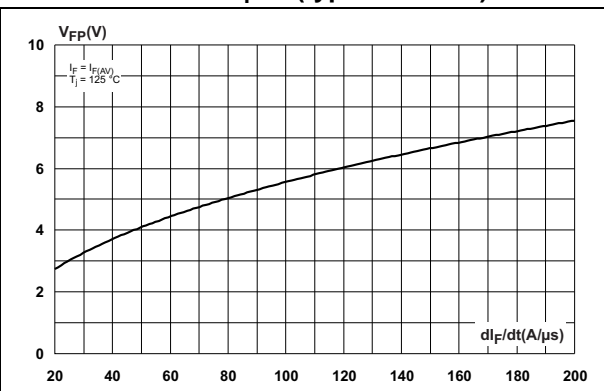


Figure 11. Forward recovery time versus di_F/dt (typical values)

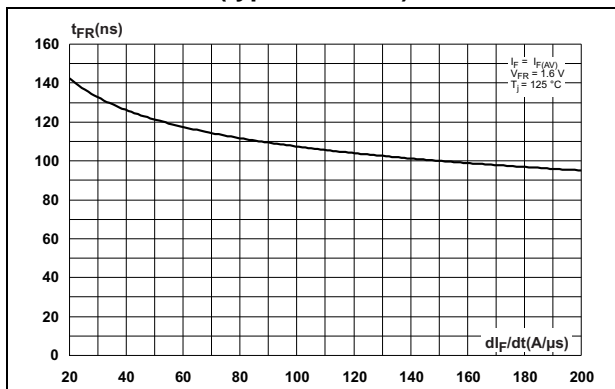


Figure 12. Junction capacitance versus reverse voltage applied (typical values)

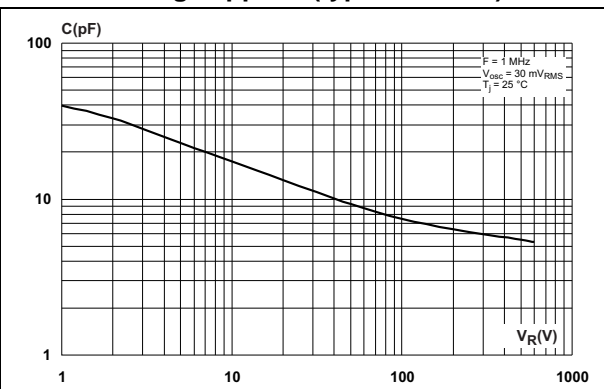
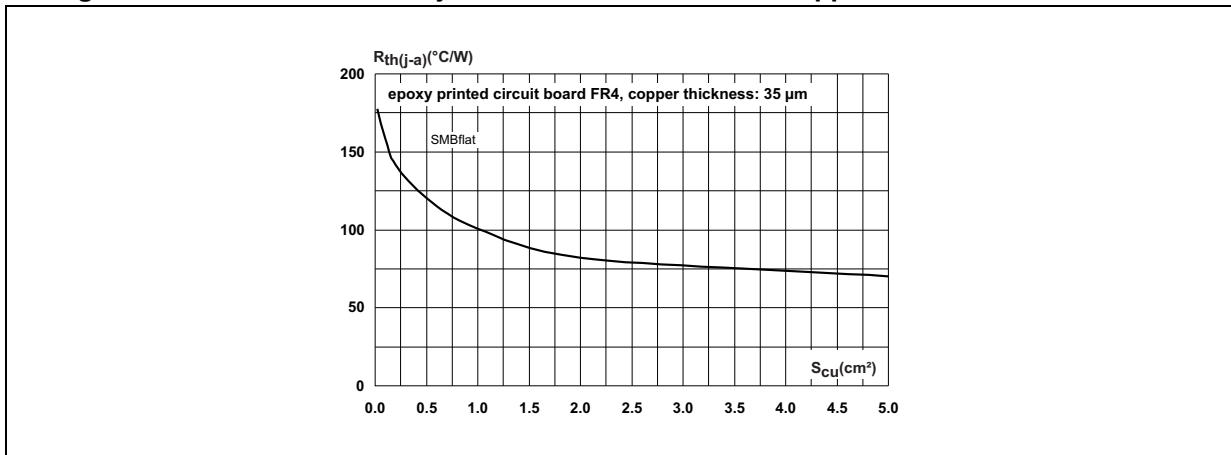


Figure 13. Thermal resistance junction to ambient versus copper surface under each lead



2 Package information

- Epoxy meets UL94,V0
- Lead-free package
- Band indicates cathode

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Figure 14. SMBflat dimensions definitions

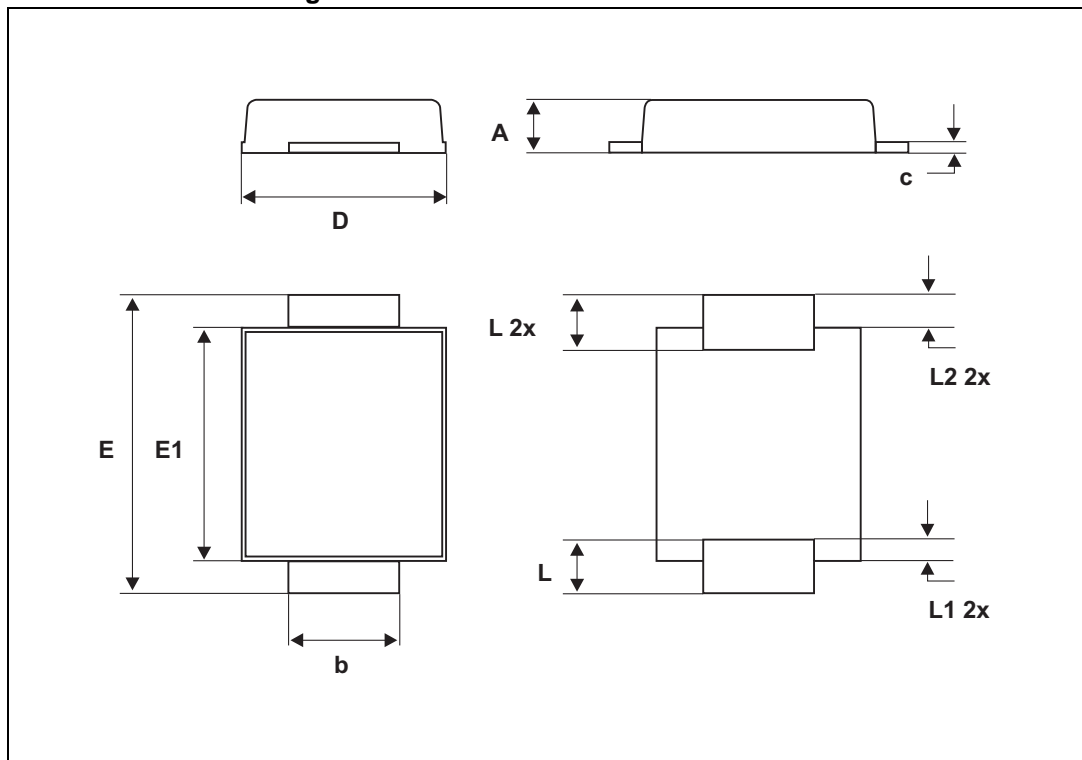
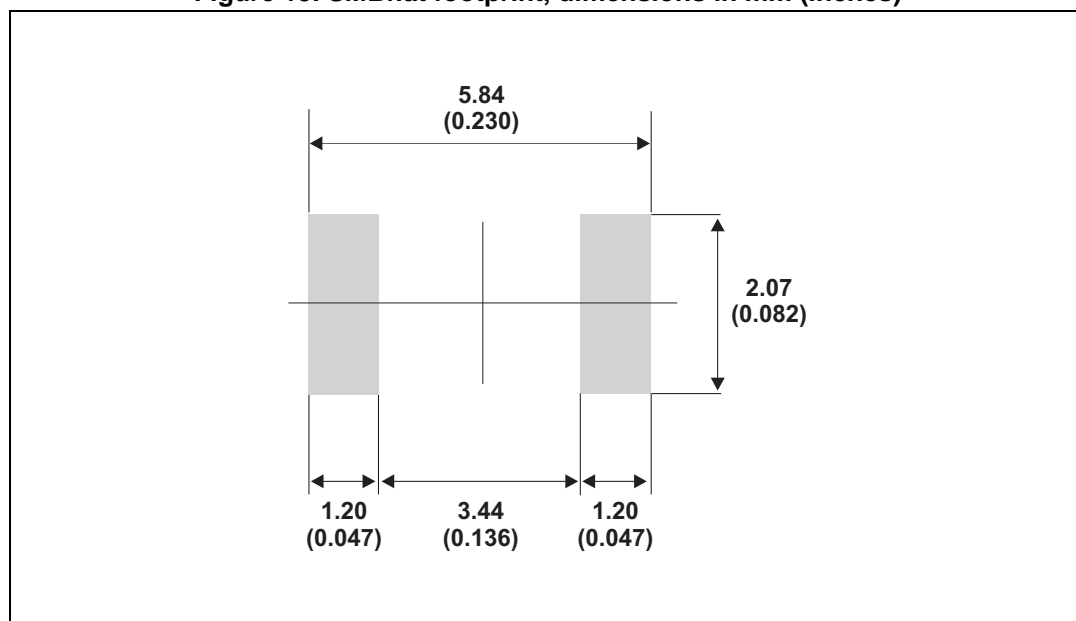


Table 6. SMBflat dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.90		1.10	0.035		0.043
b	1.95		2.20	0.077		0.087
c	0.15		0.40	0.006		0.016
D	3.30		3.95	0.130		0.155
E	5.10		5.60	0.200		0.220
E1	4.05		4.60	0.159		0.181
L	0.75		1.50	0.029		0.059
L1		0.40			0.016	
L2		0.60			0.024	

Figure 15. SMBflat footprint, dimensions in mm (inches)



3 Ordering information

Table 7. Ordering information

Order codes	Marking	Package	Weight	Base qty	Delivery mode
STTH3L06UFY	F3L6Y	SMBflat	50 mg	5000	Tape and reel

4 Revision history

Table 8. Document revision history

Date	Revision	Changes
04-Aug-2014	1	Initial release.

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2014 STMicroelectronics – All rights reserved

